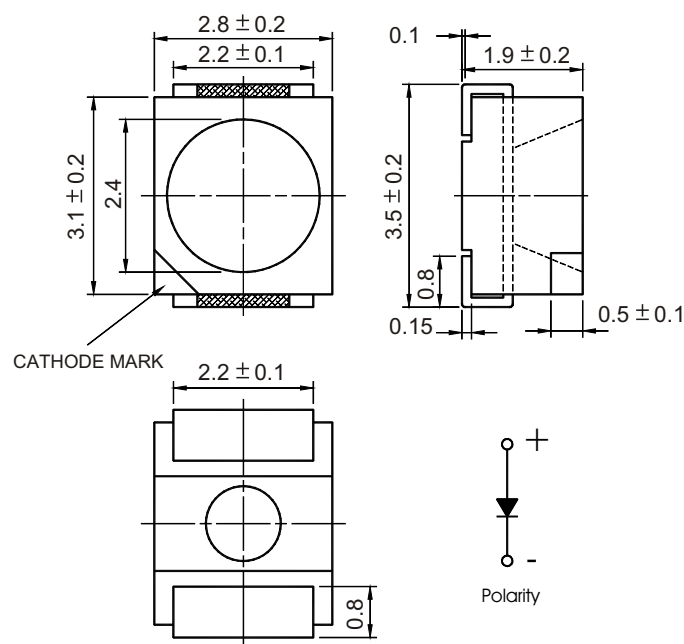




● Features:

1. Chip material: InGaN
2. Emitting color: Ultra Warm White
3. Lens Appearance: Water Clear
4. Long life-solid state reliability
5. Compatible with automatic placement equipment
6. Compatible with reflow solder process
7. RoHS compliant

● Package dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 mm (0.01 inch) unless otherwise specified.
3. Specifications are subject to change without notice.



● Absolute maximum ratings ($T_a = 25^\circ\text{C}$)

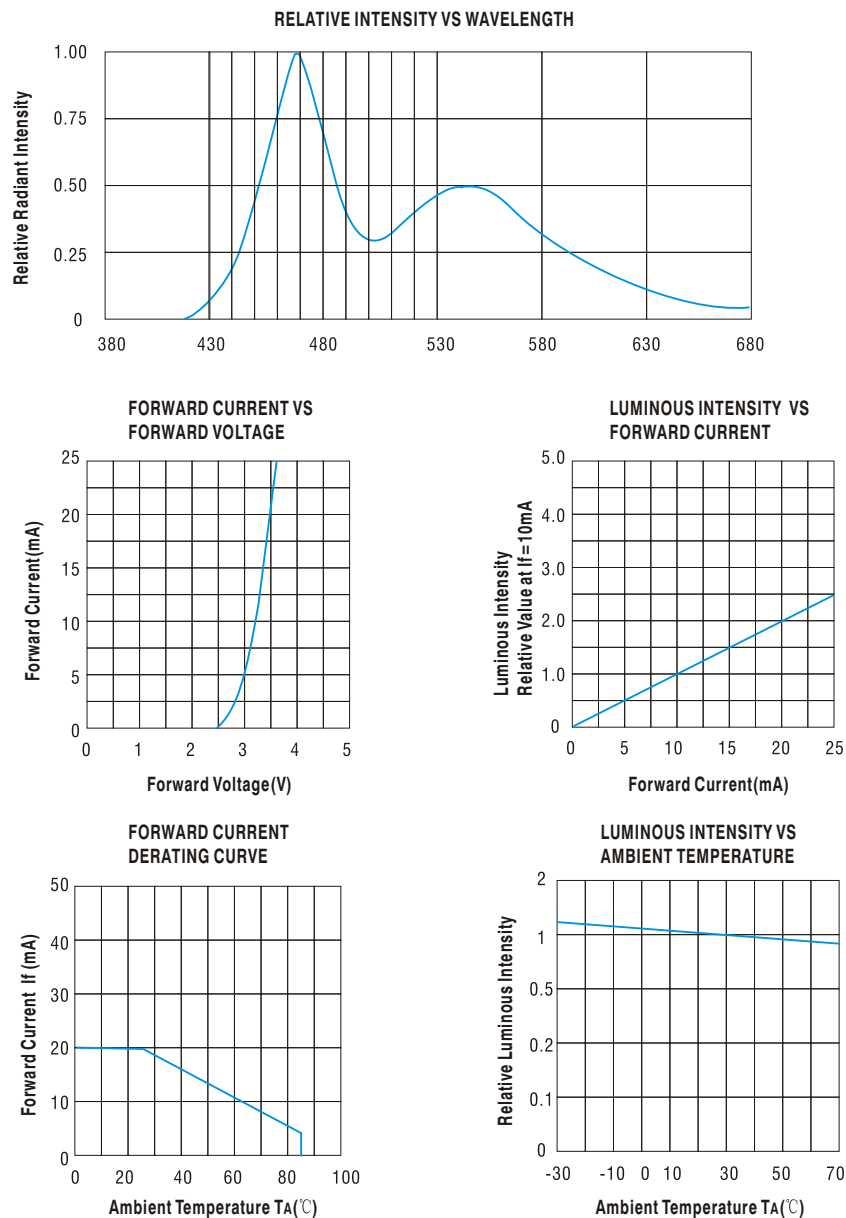
Characteristic	Test Condition	Symbol	UW	Units
Pulse Forward Current	1/10 duty cycle 0.1ms Pulse width	I_{FP}	100	mA
DC Forward Current		I_F	20	mA
Reverse Current	$V_R = 5V$	I_R	10	μA
Power Dissipation		P_D	120	mW
Operating Temperature		T_{OPR}	-40 to +80	$^\circ\text{C}$
Storage Temperature		T_{STG}	-40 to +85	$^\circ\text{C}$
Lead Soldering Temperature	1.60mm from body maximum 3 seconds	T_{SOL}	260	$^\circ\text{C}$



● Electrical And Optical Characteristics(Ta=25°C)

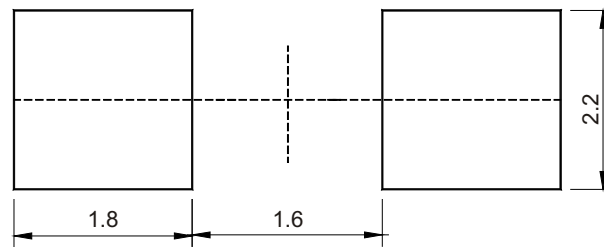
Parameter	Test Condition	Symbol	Min.	Typ.	Max.	Units
Forward Voltage	IF=20mA	V _F	---	3.20	3.80	V
Reverse Current	V _R =5V	I _R	---	---	10	μA
Chromaticity Coordinates	IF=20mA	X	0.391	---	0.510	nm
		Y	0.363	---	0.475	nm
Spectral Line Half-width	IF=20mA	△λ	---	---	---	nm
Luminous Intensity	IF=20mA	I _v	---	1200	---	mcd
Viewing Angle	IF=20mA	2θ½	---	120	---	deg.

● Typical electro-optical characteristics curves





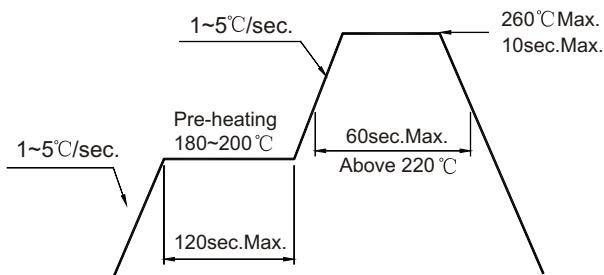
● Soldering Pad Dimensions:



● Soldering Conditions:

1.Reflow soldering profile

Lead-free solder



2.Soldering Iron

Power dissipation of iron should be smaller than 25W, and temperature should be controllable. The work must be finished within 3sec. under 300°C only once.

Do not stress its resin while soldering.

After soldering, do not warp the circuit board.

● Package Tape Specifications:(1000~2000pcs/Reel)

